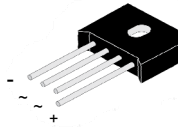
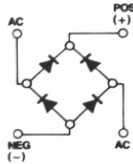


Single Phase Silicon Bridge Rectifier

Reverse voltage - 50 to 1000Volts, Forward current - 8A.



KBU



KBU8005 ~ KBU810

Package: KBU
Leaded Plastic Package
RoHS compliant

FEATURES:

1. Reliable low cost construction utilizing molded plastic technique
2. Ideal for printed circuit board
3. Low forward voltage drop
4. Mounting position :Any
5. Low reverse leakage current
6. Glass passivated chip
7. High surge current capability

ABSOLUTE MAXIMUM RATINGS ELECTRICAL CHARACTERISTICS

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%

PARAMETERS	SYMBOL	KBU 8005	KBU 801	KBU 802	KBU 804	KBU 806	KBU 808	KBU 810	UNIT
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Bridge Input Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Output Current at $T_A 50^\circ C$ ¹	$I_{(AV)}$	8.0							A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed on Rated	I_{FSM}	200							A
Maximum Forward Voltage	@4A	1.0							V
	@8A	1.1							
Maximum Reverse Current at Rated DC Blocking Voltage	@ $T_A 25^\circ C$	10.0							μA
	@ $T_A 125^\circ C$	500							
Typical Junction Capacitance per leg ¹	C_J	400							pF
Typical Thermal Resistance ²	$R_{\theta JA}$	18							$^\circ C/W$
	$R_{\theta JC}$	3							
Operating Temperature Range	T_J	-55 to +150							$^\circ C$
Storage Temperature Range	T_{STG}	-55 to +150							

Notes: 1. Measured at 1 MHz and applied reverse voltage of 4.0 VDC.

2. Unit case mounted on 4" x 6" x 0.25" Al plate heat sink.



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Typical Characteristic curves

Fig 1: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT PER BRIDGE ELEMENT

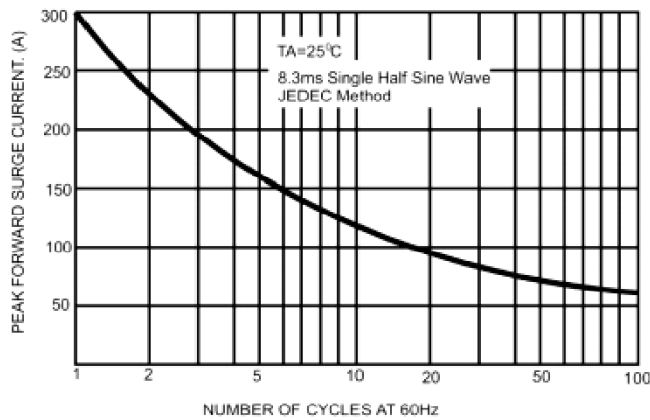


Fig 2: FORWARD CURRENT DERATING CURVE

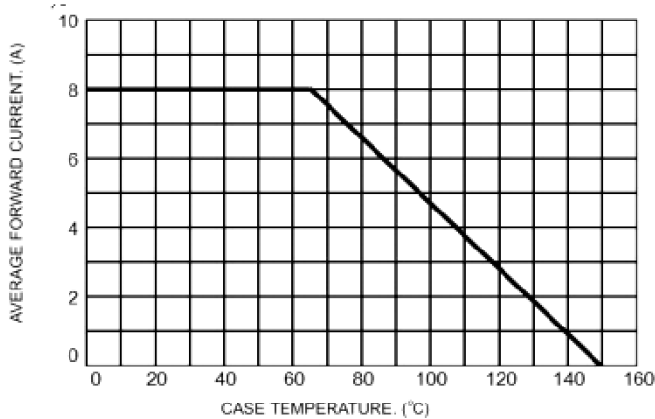


Fig 3: TYPICAL INSTANTIOUS FORWARD CHARACTERISTICS

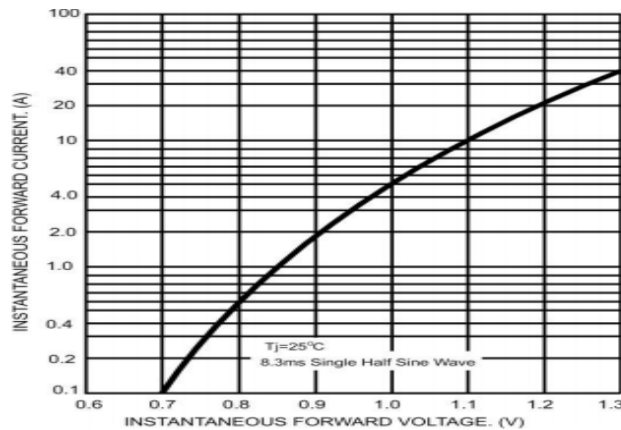


Fig 4: TYPICAL REVERSE CHARACTERISTICS PER BRIDGE ELEMENT

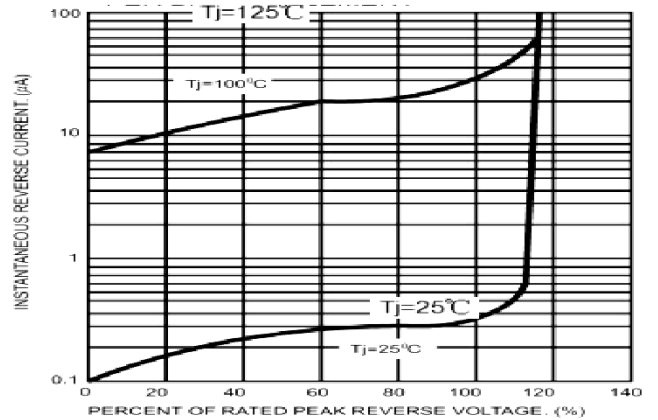
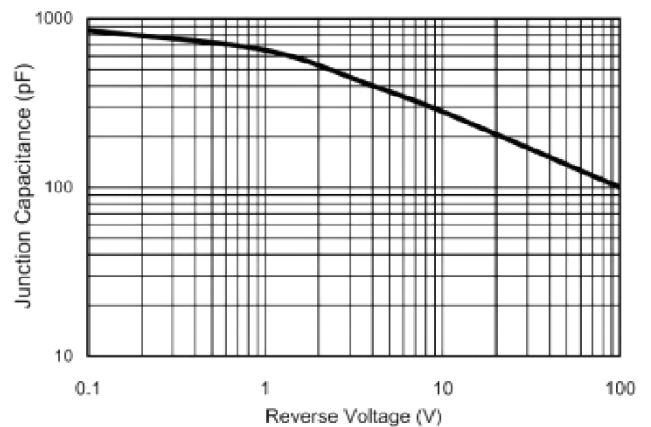
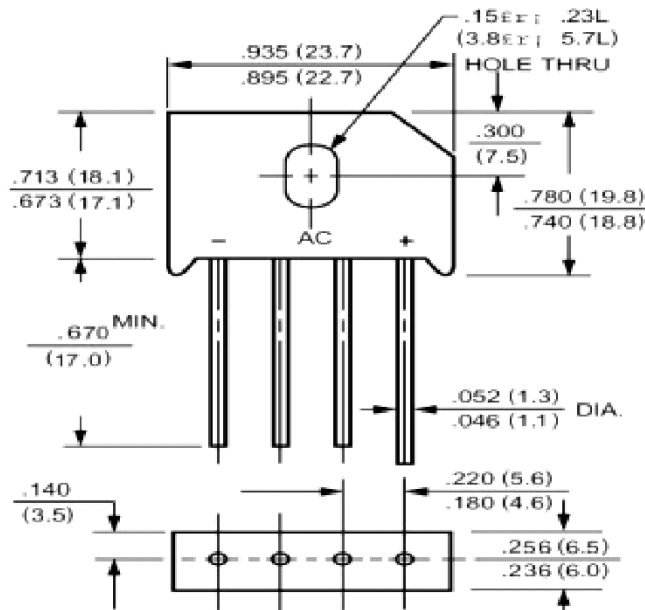


Fig 4: Typical JUNCTION CAPACITANCE



Package Details

Package: KBU



Dimensions in inches and (millimeters)

MECHANICAL DATA

1. Case: Molded plastic, KBU
2. Epoxy: UL 94V-O rate flame retardant
3. Terminals: Pure tin plated, lead free, Leads solderable per MIL-STD-202, method 208 .
4. Mounting position: As Marking
5. Weight: 8.0 gram

Packaging Information

Package/ Case Type	Packaging Type	Std. Packing Qty
KBU	Bulk	400

Bulk: Lose in Poly bags

Recommended Reflow Solder Profiles

The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.

Figure 1

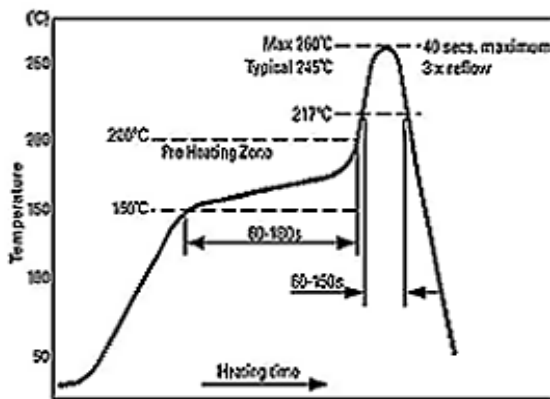
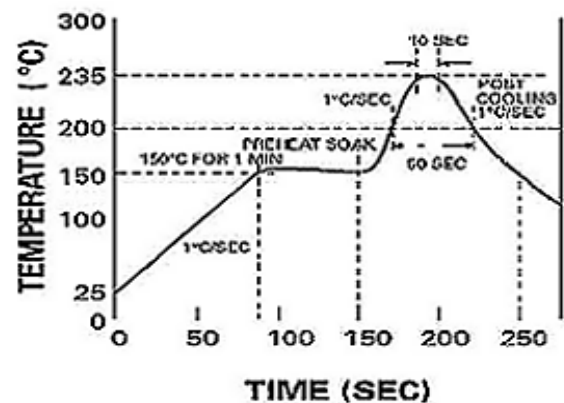


Figure 2

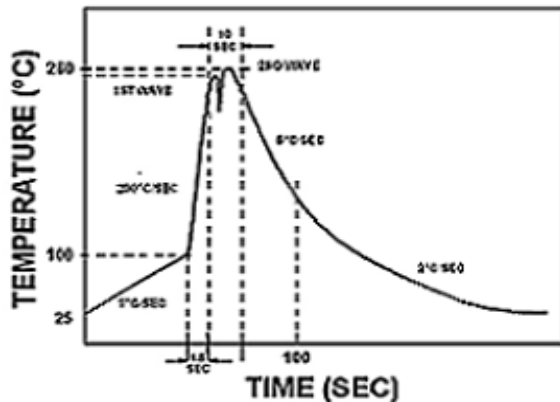


Reflow profiles in tabular form

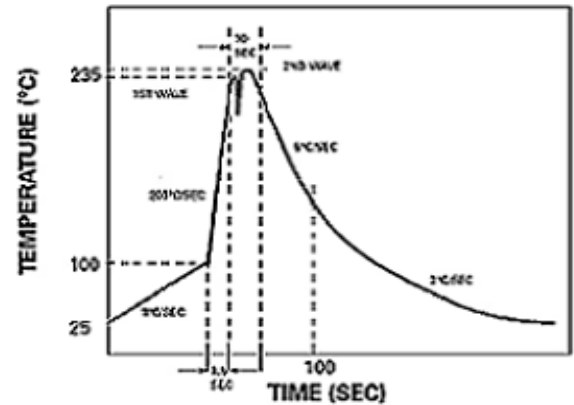
Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~3°C/second	~3°C/second
Preheat		
– Temperature Range	150-170°C	150-200°C
– Time	60-180 seconds	60-180 seconds
Time maintained above:		
– Temperature	200°C	217°C
– Time	30-50 seconds	60-150 seconds
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	40 seconds
Ramp-Down Rate	3°C/second max.	6°C/second max.

Recommended Wave Solder Profiles

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used



The Recommended solder Profile For Devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder



Wave Profiles in Tabular Form

Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~200°C/second	~200°C/second
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	10 seconds
Ramp-Down Rate	5°C/second max.	5°C/second max



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Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- Temperature 5 °C to 30 °C
- Humidity between 40 to 70 %RH
- Air should be clean.
- Avoid harmful gas or dust.
- Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- Avoid rapid change of temperature.
- Avoid condensation.
- Mechanical stress such as vibration and impact shall be avoided.
- The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

Shelf Life of CDIL Products

The shelf life of products is the period from product manufacture to shipment to customers. The product

Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start.

For this, the following JEDEC table may be referred:

JEDEC MSL Level		
Level	Time	Condition
1	Unlimited	≤30 °C / 85% RH
2	1 Year	≤30 °C / 60% RH
2a	4 Weeks	≤30 °C / 60% RH
3	168 Hours	≤30 °C / 60% RH
4	72 Hours	≤30 °C / 60% RH
5	48 Hours	≤30 °C / 60% RH
5a	24 Hours	≤30 °C / 60% RH
6	Time on Label(TOL)	≤30 °C / 60% RH



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Customer Notes

Component Disposal Instructions

1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.



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